Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	100	V
RMS Reverse Voltage	$V_{R(RMS)}$	71	V
Forward Continuous Current (Note 5)	I_{FM}	250	mA
Average Rectified Output Current (Note 5)	I_O	125	mA
Repetitive Peak Forward Current	I_{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I_{FSM}	4 1 0.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Power Dissipation (Note 5)	P_D	350	mW
Typical Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	—	V	I_R = 20μA
Forward Voltage	V_F	—	0.715 0.855 1.0 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Reverse Current (Note 6)	I_R	—	0.5 100 30 30	μA μA μA nA	V_R = 80V V_R = 80V, T_J = +150°C V_R = 25V, T_J = +150°C V_R = 25V
Total Capacitance	C_T	—	1.5	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{RR}	—	4.0	ns	I_F = I_R = 10mA, I_{RR} = 0.1 x I_R, R_L = 100Ω
Forward Recovery Voltage	V_{FR}	—	1.75	V	I_F = 10mA, t_R = 20ns

Notes: 5. Part is mounted on a 1.5"x1.5" FR-4 substrate PC board, with 1" X 1" 2oz Cu pad.
6. Short duration pulse test used to minimize self-heating effect.

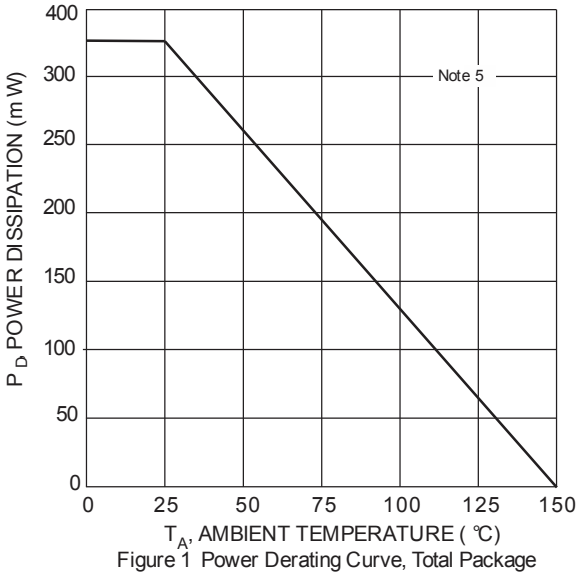

Figure 1 Power Derating Curve, Total Package

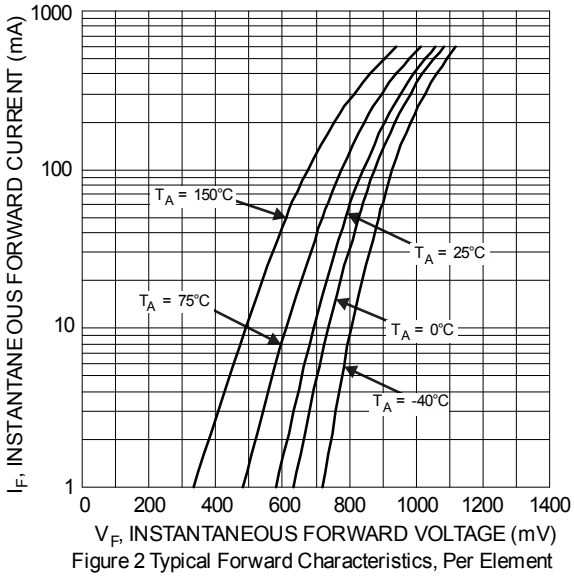

Figure 2 Typical Forward Characteristics, Per Element

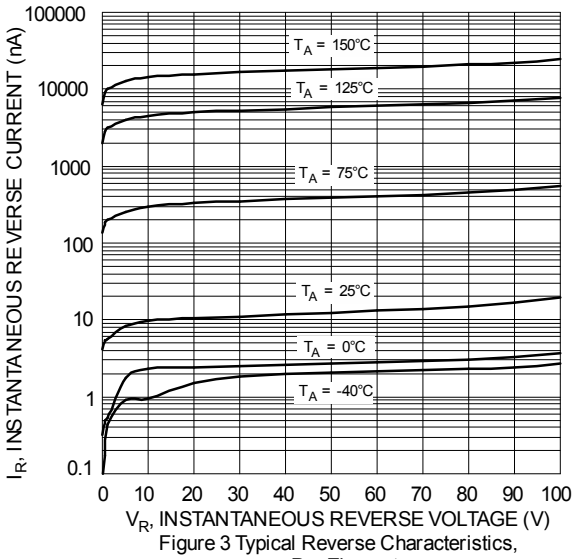

Figure 3 Typical Reverse Characteristics, Per Element

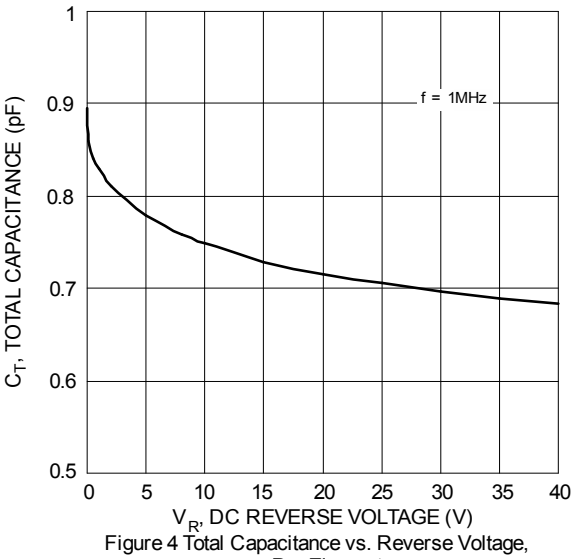

Figure 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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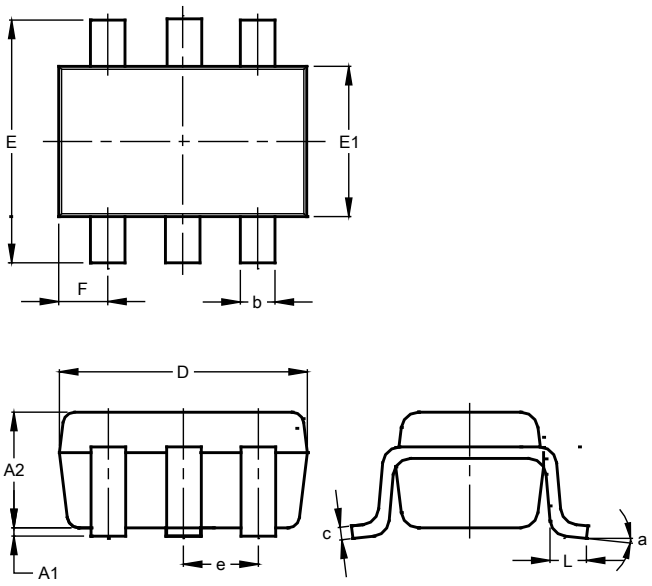

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Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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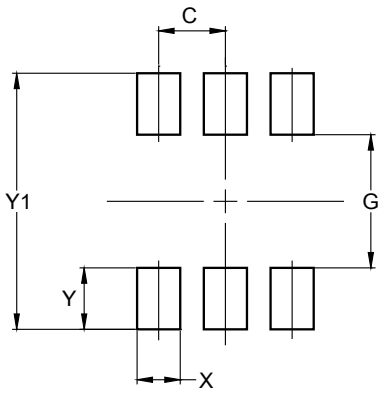

Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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